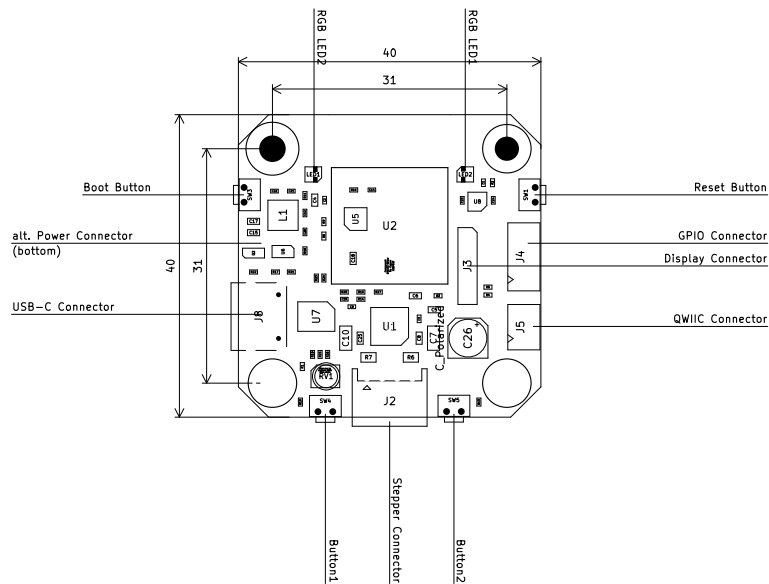


Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.06 mm	Black	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	prepreg	FR4	0.22 mm	FR4 natural	4.5	0.02
In1.Cu	copper		0.017 mm		1	0
Dielectric	core	FR4	0.41 mm	FR4 natural	4.5	0.02
In2.Cu	copper		0.017 mm		1	0
Dielectric	core	FR4	0.22 mm	FR4 natural	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.06 mm	Black	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.074 mm
Board overall dimensions:	40 mm x 40 mm		
Min track/spacing:	0.125 mm / 0.125 mm	Min hole diameter:	0.2 mm
Copper Finish:	ENIG	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		



Project: <https://github.com/nerdyscout/esp32stepper>
License: https://ohwr.org/cern_ohLw_v2.txt (CERN-OHL-W)

DE000152

Stefan Herold

Sheet:
File: esp32stepper.kicad_pcb

Title: ESP32STEPPER

Size: A4 Date: 2025-06-27

Rev: 1.0

KiCad E.D.A. 9.0.1

Id: 1/1